

Title (en)  
Primer for metallization.

Title (de)  
Primer zum Metallisieren von Substratoberflächen.

Title (fr)  
Couche de base pour métallisation.

Publication  
**EP 0485839 B1 19950104 (DE)**

Application  
**EP 91118731 A 19911104**

Priority  
DE 4036591 A 19901116

Abstract (en)  
[origin: EP0485839A2] Primers consisting essentially of a film-former or matrix-former, an additive, an ionogenic and/or colloidal noble metal, a filler and a solvent are suitable for coating substrate surfaces for subsequent chemical (electroless) metallisation.

IPC 1-7  
**C23C 18/28**

IPC 8 full level  
**C08J 7/04** (2006.01); **C09D 5/38** (2006.01); **C09D 175/00** (2006.01); **C09D 175/04** (2006.01); **C23C 18/18** (2006.01); **C23C 18/28** (2006.01); **G12B 17/02** (2006.01); **H05K 9/00** (2006.01)

CPC (source: EP US)  
**C23C 18/28** (2013.01 - EP US)

Citation (examination)

- US 3560257 A 19710202 - SCHNEBLE FREDERICK W JR, et al
- Römpps Chemie Lexikon, Band 1, 8. Auflage, 1979, Seiten 64-65
- Römpps Chemie Lexikon, Band 4, 8. Auflage, 1985, Seiten 2866-2867

Cited by  
CN109694685A; WO9909794A1

Designated contracting state (EPC)  
BE CH DE FR GB IT LI NL SE

DOCDB simple family (publication)  
**EP 0485839 A2 19920520; EP 0485839 A3 19930224; EP 0485839 B1 19950104**; CA 2055352 A1 19920517; CA 2055352 C 19991026; DE 4036591 A1 19920521; DE 59104146 D1 19950216; JP H04365872 A 19921217; US 5378268 A 19950103

DOCDB simple family (application)  
**EP 91118731 A 19911104**; CA 2055352 A 19911113; DE 4036591 A 19901116; DE 59104146 T 19911104; JP 32237691 A 19911112; US 78895791 A 19911107